

Amendments to the Claims:

1. (Currently Amended) A method of wetting a semiconductor wafer with slurry, said method comprising: using a wear ring to hold the wafer to a polishing pad, said wear ring including at least one inlet; at least one peripheral channel in inside the wear ring, said inlet being in communication with said channel inside the wear ring; and a plurality of outlets in communication with the at least one peripheral channel in which is inside the wear ring; injecting the slurry into the inlet such that the slurry goes into the peripheral channel in inside the wear ring, exits the outlets and contacts the polishing pad.
2. (Original) A method as recited in claim 1, further comprising pressing the wear ring against the polishing pad.
3. (Original) A method as recited in claim 1, wherein the polishing pad is disposed on a polishing table and said method further comprises rotating at least one of the wear ring and the polishing table.
4. (Original) A method as recited in claim 1, wherein the polishing pad is disposed on a polishing table and said method further comprises rotating both the wear ring and the polishing table.
5. (Cancelled)

Serial No.: 10/607,116

Art Unit: 3723

Page 2

6. (Currently Amended) A wear ring which is configured to hold a semiconductor wafer and is configured to be disposed on a polishing pad, said wear ring including at least one inlet; at least one peripheral channel in inside the wear ring, said inlet being in communication with said channel inside the wear ring; and a plurality of outlets in communication with the at least one peripheral channel in which is inside the wear ring, said wear ring configured such that slurry is injectable into the inlet such that the slurry goes into the peripheral channel in inside the wear ring, exits the outlets and contacts the polishing pad.

7. (Original) A wear ring as recited in claim 6, wherein said wear ring is pressable against the polishing pad.

8. (Cancelled)

Serial No.: 10/607,116

Art Unit: 3723

Page 3